

Statement of Compliance

Requested Part

28 January 2016 1604941-1 (Part 1 of 1)

UMNL BULKHEAD CONN.12 POS

Part Status: Active

Mil-Spec Certified: No

EU RoHS/ELV Code: Not EU RoHS or ELV Compliant

Solder Process Capability Code: Not applicable for solder process capability

China RoHS: Restricted Materials Above Threshold

Exemptions: Exemptions Not Applicable

Each REACH declaration statement below refers ONLY to the specific SVHCs published to the REACH Candidate List on the Month/Year indicated. TE does not currently provide a cumulative REACH statement related to the most recent Date of Inclusion, or to the total number of substances on the Candidate List.

REACH Oct 2008 SvHC Compliance: Contains REACH October 2008 SvHC(s)

SvHC 1: Bis (2-ethyl(hexyl)phthalate) (DEHP) (CAS No: 117-81-7)

@ 0.14 % wt

REACH Jan/Mar 2010 SvHC Compliance: Contains no REACH Jan/Mar 2010 SvHC(s)

REACH June 2010 SvHC Compliance: Contains no REACH June 2010 SvHC(s)

REACH December 2010 SvHC Compliance: Contains no REACH December 2010 SvHC(s)

REACH June 2011 SvHC Compliance: Contains no REACH June 2011 SvHC(s)

REACH December 2011 SvHC Compliance: Contains no REACH December 2011 SvHC(s)

REACH June 2012 SvHC Compliance: Contains no REACH June 2012 SvHC(s)

REACH December 2012 SvHC Compliance: Contains no REACH December 2012 SvHC(s)

REACH June 2013 SvHC Compliance: Contains no REACH June 2013 SvHC(s)

REACH December 2013 SvHC Compliance: Contains no REACH December 2013 SvHC(s)

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change

The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2).

Additionally, the part numbers that are as 5 of 6 compliant meet the material limits described above, except that these products have lead in the solderable interface only. These products may be suitable for use in an application that has an exemption for the use of lead in solder (e.g. servers, network infrastructure, etc.). Finished electrical and electronic products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked.

TE's information on SVHC's in articles is currently based on the European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' (Version: 2, April 2011), applying the 0.1% weight on weight concentration threshold at the finished product level. TE is aware of the European Court of Justice ruling of September 10th, 2015 stating that, in case of 'complex articles', the threshold for a SVHC must be applied to both the product as a whole and simultaneously to each of the articles forming part of its composition. To make sure our REACH information stays in line with the changed legal interpretation and industry practices, TE is monitoring evaluations of this new ruling and awaits the expected new ECHA quidance on the practical implementation.



REACH June 2014 SvHC Compliance: Contains no REACH June 2014 SvHC(s)

REACH December 2014 SvHC Compliance: Contains REACH December 2014 SvHC(s)

SvHC 1: Bis(2-ethylhexyl) phthalate (DEHP) @ 0.14 % wt

REACH June 2015 SvHC Compliance: Contains no REACH June 2015 SvHC(s)

REACH December 2015 SvHC Compliance: Not Reviewed for REACH December 2015 SvHC(s)

REACH Substance Communication Document: Download

Halogen Content: Low Halogen - Br, Cl, F, I < 900 ppm per homogenous

material. Also BFR/CFR/PVC Free

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Guy Degrieck

Manager, Product Environmental Compliance

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28 January 2016

中国电子电气产品中有害物质的名称及含量

China EEP Hazardous Substance Information



Restricted Materials Above Threshold

部件名称	有害物质					
(Component Name)	Hazardous Substance					
1604941-1	铅	汞	镉	六价铬	多溴联苯	多溴二苯醚
	(Pb)	(Hg)	(Cd)	(Cr6)	(PBB)	(PBDE)
连接器系统 (Connector Systems)	0	0	0	X	0	0

本表格依据SJ/T 11364标准的规定编制。

This table is compiled according to SJ/T 11364 standard.

- O: 表示该有害物质在该部件所有均质材料中的含量均在GB/T 26572标准规定的限量要求以下。
 Indicates that the concentration of the hazardous substance in all homogeneous materials of the part is below the relevant threshold of the GB/T 26572 standard.
- X: 表示该有害物质至少在该部件的某一均质材料中的含量超出GB/T 26572标准规定的限量要求。
 Indicates that the concentration of the hazardous substance in at least one homogeneous material of the part is above the relevant threshold of the GB/T 26572 standard.

电子电气产品的环保使用期限依据SJ/T 11388标准的规定确定。

The EPUP value of EEP is defined according to SJ/T 11388 standard.

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